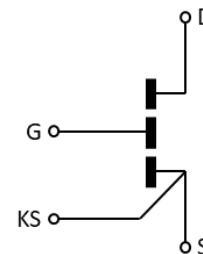
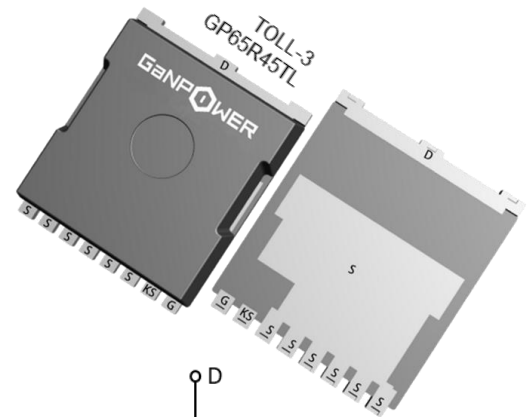
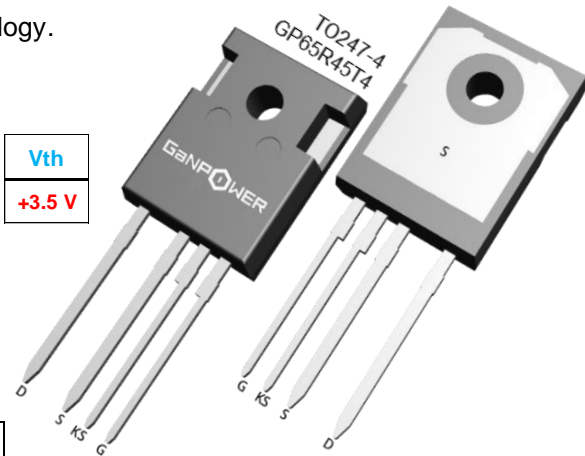


Description

The GP65R45xx is a 650V E-mode GaN transistor based on silicon technology.

Features

BVdss		Rdson@25°C		Ids@25°C		Qg	Vgs	Vth
Transient	900 V	Typ	45 mΩ	Max	30 A	6.9 nC	±20 V	+3.5 V
Continuous	650 V	Max	60 mΩ	Pulse	62 A			



Absolute Max. Ratings

	Symbols	Parameters	Value	Unit
1	Vds -max	Breakdown voltage transient @ Tcase=25°C~125°C	900	V
		Breakdown voltage continuous @ Tcase=25°C~125°C	650	V
2	Vgs -max	Gate to source max. voltage @ Tcase=25°C	-20 ~ +30	V
3	Ids-max	Drain to source max current @ Tcase=25°C, Vgs = +12 V, f=500KHz, Vbus=650V	30	A
		Drain to source max current @ Tcase=125°C, Vgs = +12 V, f=500KHz, Vbus=650V	28	A
		Drain to source pulse current @ Tcase =25°C, pulse width 10 μs, Vgs = +12 V, Vbus = 650V	62	A
4	dv/dt-max	Drain to source voltage slew rate	200	V/ns
5	TJ -max	Max junction temperature	150	°C
6	TS -storage	Storage temperature	-55 ~ 150	°C
7	TJ -operate	Operating temperature	-55 ~ 150	°C

Thermal and Soldering Characteristics

	Symbols	Parameters	Value	Unit	Package
1	RthJC	Thermal resistance (junction to case)	0.6	°C/W	TO247-4
			0.27		TOLL-3
2	RthJA	Thermal resistance (junction to ambient)	62	°C/W	TO247-4
			40		TOLL-3
3	Tsolder	Reflow soldering temperature	260	°C	All

Ordering Information

Order Code	Package Type	Packaging	Qty
GP65R45T4	TO247-4	Tube	30
GP65R45TL	TOLL-3 PG-HSOF-8-3	Tape-and-Reel	2000

Device Characteristics

Static Parameters				Test data				
	Parameters		Conditions	Min	Typical	Max	Unit	
1	V _{gs} (TH)	Gate threshold voltage	V _{ds} =V _{gs} , I _d =21 mA (T _j =25 °C)	3.0	3.5	4.0	V	
2	V _{gs} ¹	Gate-Source voltage range		-20	12	20	V	
3	BV _{dss} ²	Drain-Source breakdown voltage	V _{gs} =0V, I _d < 1 mA (T _j =25 °C)		650		V	
4	I _{dss}	Zero gate voltage drain leakage current	V _{gs} =0V, V _{ds} = 700V T _j = 25 °C		1.3	2.0	μA	
5	I _{gss}	Gate-Source Leakage	V _{gs} = 6V, V _{ds} = 0V		0.7	30	mA	
6	R _{dson}	drain-source on resistance	V _{gs} =6V, I _d =0.8A T _j = 25 °C		45	60	mΩ	
7	V _{sd}	Reverse conduction voltage	I _{sd} =0.12A, V _{gs} =0V	1.2	2.0	3	V	
8	R _g	Gate resistance	f=25Mhz Open drain		1.5		Ω	
Dynamic Parameters				Test data				
	Parameters		Conditions	Min	Typical	Max	Unit	
1	C _{iss}	Input capacitance	V _{gs} = 0 V V _{ds} = 700 V f = 1MHz		10		pf	
2	C _{oss}	Output capacitance				72		pf
3	C _{rss}	Reverse transfer capacitance				4.6		pf
4	Q _g	Gate charge	V _{ds} = 400V I _d = 9A V _{gs} = 6V		6.9		nC	
5	Q _{gs}	Gate to source charge				1.5		nC
6	Q _{gd}	Gate to drain charge				1.8		nC
7	Q _{rr}	Reverse recovery charge			0		nC	
Switching Performance				Test data				
	Parameters		Conditions	Min	Typical	Max	Unit	
1	t _d (on)	Turn-on delay time	V _{ds} = 800V I _d = 15A R _g = 10Ω V _{gs} = -3/6.5V		34		ns	
2	t _r	Rise time				26		ns
3	t _d (off)	Turn-off delay time				33		ns
4	t _f	Fall time				20		ns

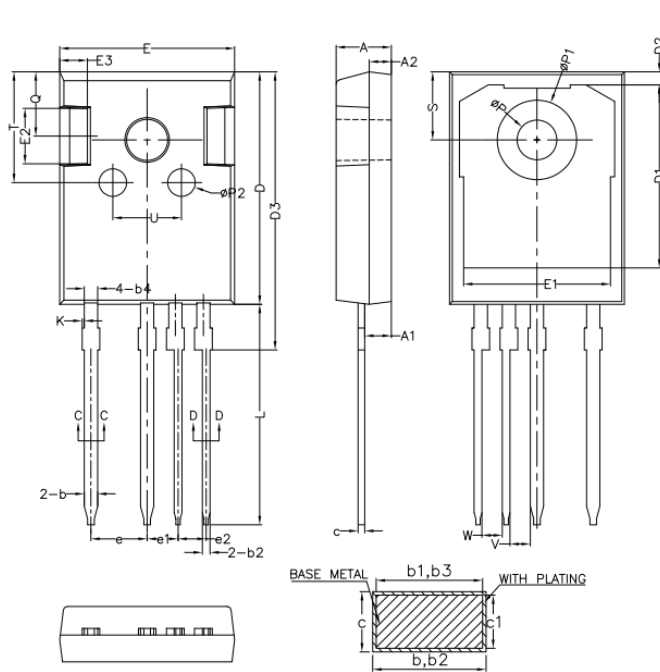
¹ A wider range of gate driving from -20V to 20V can be accepted, but recommended range is still 0V to +12V.

Wider range protects the gate from damage, but at some cost of power loss.

² BV_{dss} refers to DC withstanding voltage. This product is recommended for DC bus voltage of 400V-650V.

Package Information

TO247-4



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16	-	1.29
b1	1.15	1.20	1.25
b2	0.66	-	0.79
b3	0.65	0.70	0.75
b4	1.16	-	1.29
c	0.59	-	0.66
c1	0.58	0.60	0.62
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
D3	24.97	25.12	25.27
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	4.98	5.08	5.18
e1	2.69	2.79	2.89
e2	2.44	2.54	2.64
K	0	-	0.20
L	19.80	19.92	20.10
P	3.50	3.60	3.70
P1	-	-	7.40
P2	2.40	2.50	2.60
Q	5.60	-	6.00
S	6.00	6.15	6.30
T	9.80	-	10.20
U	6.00	-	6.40
V	1.44	1.84	2.24
W	1.44	1.84	2.24

NOTES:
1. ALL DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
2. EJECTION MARK DEPTH 0.10 ± 0.05 .

TOLL-3

